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Kiru · Kezuru · Migaku Technologies



Fully Automatic Dicing Saw **DFD6760**

**High-end model dicing saw
for $\varnothing 300$ mm wafers**

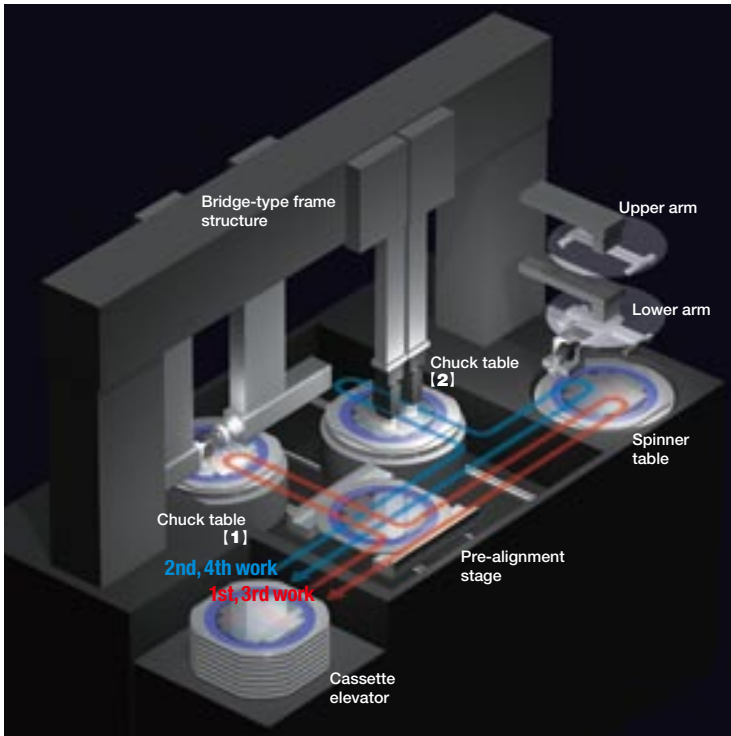


Fully automatic dual-spindle dicing saw with two chuck tables to improve productivity

- The DFD6760 is the high-end model whose productivity has further enhanced from the DFD6362 fully automatic dicing saw for $\varnothing 300$ mm wafers widely accepted since its launch in 2008.
- Since this dicing saw has two chuck tables, it is possible to transport and align on one chuck table while processing on the other chuck table. This shortens the spindle waiting time for processing and improves productivity.
- Faster feed speed of the X, Y and Z-axes (same as the DFD6362) also reduces the processing time.



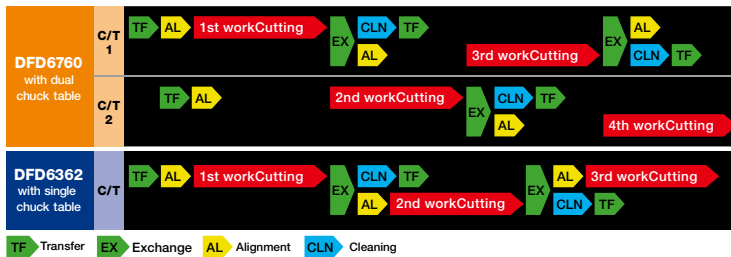
Fully Automatic Dicing Saw DFD6760



DFD6760 Specifications

Workpiece size		Max. ϕ 300
Number of chuck tables	PCS	2
X-axis	Cutting range	mm 310
	Cut speed	mm/s 0.1 ~ 1000
Y1-axis and Y2-axis	Cutting range	mm 310
	Index step	mm 0.0001
	Index positioning accuracy	mm 0.003/310 (Single error) 0.002 or less/5
Z-axis	Max. stroke	mm 14.7 (for 2" blade)
	Moving resolution	mm 0.0005
	Repeating accuracy	mm 0.001
	Max. blade size	mm ϕ 58
θ-axis	Max. rotating angle	deg 380
Spindle Output		kW 1.2 at 60,000 min ⁻¹ 1.2 at 80,000 min ⁻¹ (Option)
	Rated Torque	N·m 0.19
	Revolution speed range	min ⁻¹ 6,000 ~ 60,000 6,000 ~ 80,000 (Option)
Applicable tape frame		2-12
Utilities	Power supply	200 ~ 240 V AC \pm 10 %, 3-phase(50/60 Hz) <small>For other than the above voltages, a transformer is necessary.</small>
	Power consumption	When processing kW 2.5 During warm-up kW 1.6
	Air pressure	MPa 0.5 ~ 0.8
	Average air consumption during operation	L/min(ANR) 200.0
	Clean air pressure	MPa 0.5 ~ 0.8
	Average clean air consumption during operation	L/min(ANR) 65.0
	Cutting water, water curtain and other	-
	Water pressure	MPa 0.2 ~ 0.4
	Max. consumption flow rate	L/min Cutting water: 12 Water curtain: 1 x 2 unit Other: 1
	Cooling water	Water pressure MPa 0.2 ~ 0.4 Consumption flow rate L/min 3.0 at 0.3 MPa
	Exhaust duct capacity	m ³ /min 5.0
	Machine size (W x D x H)	mm 1,200 x 1,900 x 1,800
	Machine weight	kg Approx.2,800 (without transformer for overseas use) Approx.2,900 (with transformer for overseas use)

Process Flow Comparison with Existing Model



Enhanced processing quality and throughput

When processing a thin wafer with DAF, controlling the cut depth from the wafer surface is important. The NSD (non-contact surface detector), which is used to control the cut depth, takes about 10 seconds for measurement and this is a cause of low productivity. For the DFD6760, the NSD can be used on one chuck table when processing a wafer on the other chuck table, so this can prevent throughput deterioration.

Various measures to prevent particles

The cut section atomizing nozzle, wheel cover, and chuck table water curtain, which are well received in the DFD6362, are selectable as optional accessory in accordance with workpiece characteristics.

Easy operation

The GUI (graphical user interface), which is recognized as easy to use in the DFD6362, is also used. Combining this with the LCD touch panel achieves stress-free operation.

Environmental conditions

- Use clean, oil-free air at a dew point of -15 °C or less. Use a residual oil: 0.1 ppm 1 Wt/Wt. Filtration rating: 0.01 μ m/99.5% or more.
 - Keep room temperature fluctuations within \pm 1 °C of the set value. Set value should be between 20 - 25 °C.
 - Keep cutting water and cleaning water 2 °C above room temperature (fluctuations within \pm 1 °C).
 - Keep spindle cooling water the same as room temperature (20 - 25 °C, fluctuations within \pm 1 °C).
 - The machine should be used in an environment free from external vibrations. Do not install machine near a ventilation opening, heat-generating equipment, or oil mist-generating equipment.
 - This machine uses water. In case of water leakage, please install the machine on the floor with sufficient waterproofing and drainage treatments.
- * All the pressures are described using a gauge pressure.
* The above specifications may change due to technical modifications. Please confirm when placing your order.
* For further information, please contact your local sales representatives.



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